

NOTES, UNLESS OTHERWISE SPECIFIED:

- The netname "V5P0V" represents connection to the +5.0V power buss.
- The netname "V5P0VF" represents connection to the +5.0V filtered power buss.
- The netname "V3P3V" represents connection to the +3.3V power buss
- The netname "V2P5VREF" represents connection to the +2.5V reference buss
- The netname "V2P5VREFBUF" represents connection to the +2.5V buffered reference buss.
- The netname "GND" represents connection to the ground plane.
- A "Z" suffix on a signal name indicates an active low signal.
- All components with designators "U*", "Q*", and "D*" are electrostatic discharge sensitive.
- All resistor values are in ohms.
- All capacitor values in microfarads unless otherwise specified.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	04/16/2014	HPC
A	ECO 2141383: REV A Release	05/22/2014	HPC

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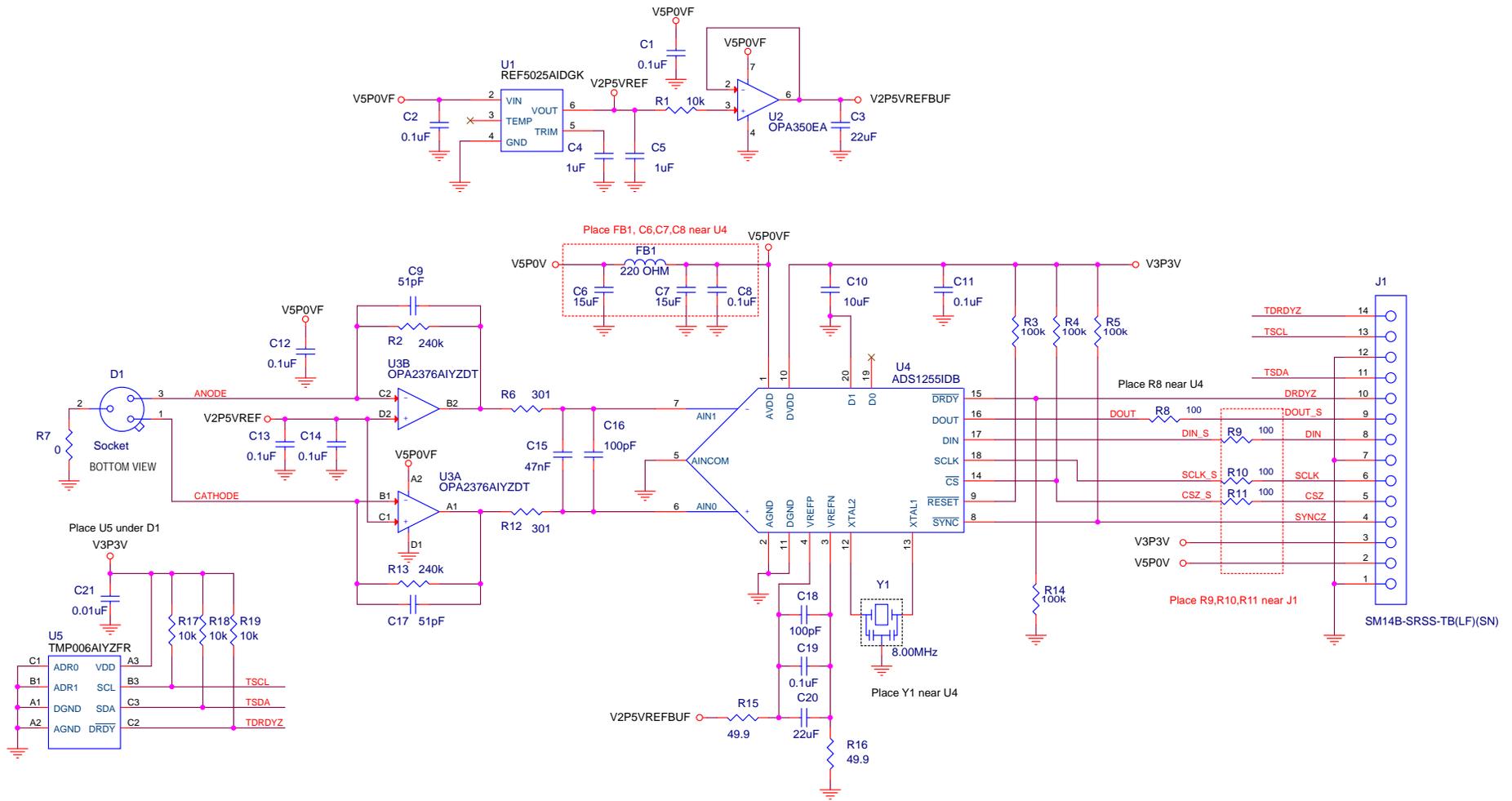
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	DWN	DATE	05/22/2014	TEXAS INSTRUMENTS (C) COPYRIGHT 2014 TEXAS INSTRUMENTS ALL RIGHTS RESERVED
	ENGR		05/22/2014	
	APVD		05/22/2014	
	MFG			TITLE
	0314CP	QA		ESD, Mobile Spectroscopy Detector Board
NEXT ASSY	USED ON			DRAWING NO
				A3 2514020
				REV
				B
APPLICATION	SW	Allegro Design Entry 16.6		SCALE
				SHEET 1 of 3



TEXAS INSTRUMENTS	DWN	DATE 05/22/2014	A3	DRAWING NO 2514020	REV B
	ISSUE DATE	SCALE			

Revision History

Rev. -- : Draft Release ~ 04/16/2014

Rev. A: ECO 2141383: ~ 05/22/2014

Rev. B: C9, C17 change value to 51pF, C15 change value to 47nF: ~ 11/03/2014 MR.

Schematic Revision History

TEXAS INSTRUMENTS	DWN	DATE	A3	DRAWING NO	2514020	REV	B
	ISSUE DATE	05/22/2014					
SCALE				SHEET 3 OF 3			